ABSOLUTE MAXIMUM RATINGS

Power Requirements

Note 1: The outputs may be shorted to AGND, provided that the power dissipation of the package is not exceeded. Typical short-circuit current to AGND is 25mA

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS—Dual Supplies

(V_{DD} = +11.4V to +16.5V, V_{SS} = -5V ±10%, AGND = DGND = 0V, V_{REF} = +2V to (V_{DD} - 4V), T_A = T_{MIN} to T_{MAX}, unless otherwise noted.)

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ELECTRICAL CHARACTERISTICS—Dual Supplies (continued)

 $(V_{DD} = +11.4V$ to $+16.5V$, $V_{SS} = -5V \pm 10\%$, AGND = DGND = 0V, $V_{REF} = +2V$ to $(V_{DD} - 4V)$, $T_A = T_{MIN}$ to T_{MAX} , unless otherwise noted.)

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ELECTRICAL CHARACTERISTICS—Single Supply

 $(V_{DD} = +15V \pm 5\%$, $V_{SS} = AGND = DGND = 0V$, $V_{REF} = 10V$, $T_A = T_{MIN}$ to T_{MAX} , unless otherwise noted.)

Note 2: Guaranteed by design. Not production tested.

Note 3: $T_A = +25^{\circ}C$, $V_{REF} = 10kHz$, 10V peak-to-peak sine wave.

Note 4: LOAD has a weak internal pull-up resistor to V_{DD}.

Note 5: DAC switched from all 1s to all 0s, and all 0s to all 1s code.

Note 6: Sample tested at +25°C to ensure compliance.

Note 7: Slow rise and fall times are allowed on the digital inputs to facilitate the use of opto-couplers. Only timing for SCL is given because the other digital inputs should be stable when SCL transitions.

__Typical Operating Characteristics

____________________________Typical Operating Characteristics (continued)

_______________Detailed Description

The MAX500 has four matched voltage-output digital-toanalog converters (DACs). The DACs are "inverted" R-2R ladder networks which convert 8 digital bits into equivalent analog output voltages in proportion to the applied reference voltage(s). Two DACs in the MAX500 have a separate reference input while the other two DACs share one reference input. A simplified circuit diagram of one of the four DACs is provided in Figure 1.

Figure 1. Simplified DAC Circuit Diagram

VREF Input

The voltage at the VREF pins (pins 4, 12, and 13) sets the full-scale output of the DAC. The input impedance

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of the VREF inputs is code dependent. The lowest value, approximately 11kΩ (5.5kΩ for VREFA/B), occurs when the input code is 01010101. The maximum value of infinity occurs when the input code is 00000000. Because the input resistance at VREF is code dependent, the DAC's reference sources should have an output impedance of no more than 20Ω (no more than 10Ω for VRFFA/B). The input capacitance at VRFF is also code dependent and typically varies from 15pF to 35pF (30pF to 70pF for VREFA/B). VOUTA, VOUTB, VOUTC, and VOUTD can be represented by a digitally programmable voltage source as:

$V_{\text{OUT}} = N_{\text{b}} \times V_{\text{REF}} / 256$

where N_b is the numeric value of the DAC's binary input code.

Output Buffer Amplifiers

All voltage outputs are internally buffered by precision unity-gain followers, which slew at greater than 3V/µs. When driving 2kΩ in parallel with 100pF with a full-scale transition (OV to $+10V$ or $+10V$ to 0V), the output settles to \pm 1/2LSB in less than 4 μ s. The buffers will also drive 2k Ω in parallel with 500pF to 10V levels without oscillation. Typical dynamic response and settling performance of the MAX500 is shown in Figures 2 and 3.

A simplified circuit diagram of an output buffer is shown in Figure 4. Input common-mode range to AGND is provided by a PMOS input structure. The output circuitry incorporates a pull-down circuit to actively drive VOUT to within +15mV of the negative supply (V_{SS}). The buffer circuitry allows each DAC output to

Figure 2. Positive and Negative Settling Times

Figure 3. Dynamic Response

sink, as well as source up to 5mA. This is especially important in single-supply applications, where Vss is connected to AGND, so that the zero error is kept at or under $1/2LSB$ (VREF = +10V). A plot of the Output Sink Current vs. Output Voltage is shown in the Typical Operating Characteristics section.

Digital Inputs and Interface Logic

The digital inputs are compatible with both TTL and 5V CMOS logic; however, the power-supply current (I_{DD}) is somewhat dependent on the input logic level. Supply current is specified for TTL input levels (worst case) but is reduced (by about 150µA) when the logic inputs are driven near DGND or 4V above DGND.

Do not drive the digital inputs directly from CMOS logic running from a power supply exceeding 5V. When driv-

Figure 4. Simplified Output Buffer Circuit

ing SCL through an opto-isolator, use a Schmitt trigger to ensure fast SCL rise and fall times.

The MAX500 allows the user to choose between a 3-wire serial interface and a 2-wire serial interface. The choice between the 2-wire and the 3-wire interface is set by the LOAD signal. If the LOAD is allowed to float (it has a weak internal pull-up resistor to V_{DD}), the 2-wire interface is selected. If the LOAD signal is kept to a TTL-logic high level, the 3-wire interface is selected.

3-Wire Interface

The 3-wire interface uses the classic Serial Data (SDA), Serial Clock (SCL), and LOAD signals that are used in standard shift registers. The data is clocked in on the falling edge of SCL until all 10 bits (8 data bits and 2 address bits) are entered into the shift register.

Figure 5. 3-Wire Mode

Figure 6. 2-Wire Mode

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A low level on LOAD line initiates the transfer of data
from the shift register to the addressed input register.
The data can stay in this register until all four of the
input registers are updated. Then all of the DAC reg from the shift register to the addressed input register. The data can stay in this register until all four of the input registers are updated. Then all of the DAC registers can be simultaneously updated using the LDAC (load DAC) signal. When LDAC is low, the input register's data is loaded into the DAC registers (see Figure 5 for timing diagram). This mode is cascadable by connecting Serial Output (SRO) to the second chip's SDA pin. The delay of the SRO pin from SCL does not cause setup/hold time violations, no matter how many MAX500s are cascaded. Restrict the voltage at LDAC and LOAD to +5.5V for a logic high.

2-Wire Interface

The 2-wire interface uses SDA and SCL only. LOAD must be floating or tied to V_{DD} . Each data frame (8 data bits and 2 address bits) is synchronized by a timing relationship between SDA and SCL (see Figure 6 for the timing diagram). Both SDA and SCL should normally be high when inactive. A falling edge of SDA (while SCL is high) followed by a falling edge of SCL (while SDA is low) is the start condition. This always loads a 0 into the first bit of the shift register. The shift register is extended to 11 bits so this "data" will not affect the input register information. The timing now follows the 3 wire interface, except the SDA line is not allowed to change when SCL is high (this prevents the MAX500 from retriggering its start condition). After the last data bit is entered, the SDA line should go low (while the SCL line is low), then the SCL line should rise followed by the SDA line rising. This is defined as the stop condition, or end of frame.

Cascading the 2-wire interface can be done, but the user must be careful of both timing and formatting. Timing must take into account the intrinsic delay of the SRO pin from the internally generated start/stop conditions. The ts2 value should be increased by n times tp1 (where $n =$ number of cascaded MAX500s). The t_{LDS} value should also be increased by n times tp_1 . No other timing parameters need to be modified. A more serious concern is one of formatting. Generally, since each frame has a start/stop condition, each chip that has data cascaded through it will accept that data as if it were its own data. Therefore, to circumvent this limitation, the user should not generate a stop bit until all DACs have been loaded. For example, if there are three MAX500s cascaded in the 2-wire mode, the data transfer should begin with a start condition, followed by 10 data bits, a zero bit, 10 data bits, a zero bit, 10 data bits, and then a stop condition. This will prevent each MAX500 from decoding the middle data for itself.

The data is entered into the shift register in the following order:

where address bits A1 and A0 select which DAC register receives data from the internal shift register. Table 1 lists the channel addresses. D7 (MSB) through D0 is the data byte.

Since LDAC is asynchronous with respect to SCL, SDA, and LOAD, care must be taken to assure that incorrect data is not latched through to the DAC registers. If the 3-wire serial interface is used, LDAC can be either tied low permanently or tied to $\overline{\text{LOAD}}$ as long as t_{LDS} is always maintained. However, if the 2-wire interface is used, LDAC should not fall before the stop condition is internally detected. (This is the reason for the t_{LDS} delay of LDAC after the last rising edge of SDA.)

Table 1. DAC Addressing

Table 2. Logic Input Truth Table

Notes:

 $H =$ Logic High $2W = 2-Wire$ $L =$ Logic Low $3W = 3$ -Wire $M = TTL$ Logic High $F =$ Falling Edge X = Don't Care

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The SRO output swings from V_{DD} to DGND. Cascading to other MAX500s poses no problem. If SRO is used to drive a TTL-compatible input, use a clamp diode between TTL +5V and V_{DD} and the current-limiting resistor to prevent potential latchup problems with the 5V supply.

Table 2 shows the truth table for SDA, SCL, LOAD, and LDAC operation. Figures 5 and 6 show the timing diagrams for the MAX500.

__________Applications Information

Power-Supply and Reference Operating Ranges

The MAX500 is fully specified to operate with V_{DD} between $+12V \pm 5\%$ and $+15V \pm 10\%$ (+11.4V to $+16.5V$), and with Vss from OV to $-5.5V$. 8-bit performance is also guaranteed for single-supply operation (V_{SS} = 0V), however, zero-code error is reduced when V_{SS} is -5V (see *Output Buffer Amplifiers section*).

For an adequate DAC and buffer operating range, the VREF voltage must always be at least 4V below V_{DD}. The MAX500 is specified to operate with a reference input range of $+2V$ to V_{DD} - 4V.

Ground Management

Digital or AC transient signals between AGND and DGND will create noise at the analog outputs. It is recommended that AGND and DGND be tied together at the DAC and that this point be tied to the highest quality ground available. If separate ground buses are used, then two clamp diodes (1N914 or equivalent) should be connected between AGND and DGND to keep the two

Figure 7. Suggested MAX500 PC Board Layout for Minimizing Crosstalk

ground buses within one diode drop of each other. To avoid parasitic device turn-on, AGND must not be allowed to be more negative than DGND. DGND should be used as supply ground for bypassing purposes.

Figure 9. Bipolar Output Circuit

Table 3. Unipolar Code Table Table 4. Bipolar Code Table

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Note: $1 \text{LSB} = (\text{V}_{REF}) (2^{-8}) = +\text{V}_{REF} (\frac{1}{256})$

Careful PC board ground layout techniques should be used to minimize crosstalk between DAC outputs, the reference input(s), and the digital inputs. This is particularly important if the reference is driven from an AC source. Figure 7 shows suggested PC board layouts for minimizing crosstalk.

Unipolar Output

In unipolar operation, the output voltages and the reference input(s) are the same polarity. The unipolar circuit configuration is shown in Figure 8 for the MAX500. The device can be operated from a single supply with a slight increase in zero error (see Output Buffer Amplifiers section). To avoid parasitic device turn-on, the voltage at VREF must always be positive with respect to AGND. The unipolar code table is given in Table 3.

Bipolar Output

Each DAC output may be configured for bipolar operation using the circuit in Figure 9. One op amp and two resistors are required per channel. With $R1 = R2$:

$$
V_{OUT} = V_{REF} (2DA - 1)
$$

where D_A is a fractional representation of the digital word in Register A.

Table 4 shows the digital code versus output voltage for the circuit in Figure 9.

Note: $1 \text{LSB} = (V_{REF}) (2^{-8}) = +V_{REF} \left(\frac{1}{256}\right)$

Offsetting AGND

AGND can be biased above DGND to provide an arbitrary nonzero output voltage for a "zero" input code. This is shown in Figure 10. The output voltage at Vou_TA is:

$$
V_{OUT}A = V_{BIAS} + D_A V_{IN}
$$

where DA is a fractional representation of the digital input word. Since AGND is common to all four DACs, all outputs will be offset by VBIAS in the same manner. Since AGND current is a function of the four DAC codes, it should be driven by a low-impedance source. VBIAS must be positive.

Using an AC Reference

In applications where VREF has AC signal components, the MAX500 has multiplying capability within the limits of the VREF input range specifications. Figure 11 shows a technique for applying a sine-wave signal to the reference input, where the AC signal is biased up before being applied to VREF. Output distortion is typically less than 0.1% with input frequencies up to 50kHz, and the typical -3dB frequency is 700kHz. Note that VREF must never be more negative than AGND.

Generating VSS

The performance of the MAX500 is specified for both dual and single-supply ($VSS = OV$) operation. When the improved performance of dual-supply operation is desired, but only a single supply is available, a -5V Vss supply can be generated using an ICL7660 in one of the circuits of Figure 12.

Digital Interface Applications

Figures 13 through 16 show examples of interfacing the MAX500 to most popular microprocessors.

Figure 12. Generating -5V for V_{SS}

/VI/IXI/VI

Figure 13. 80C51 Interface Figure 14. Z-80 with Z8420 PIO Interface

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Figure 15. 8085/8088 with Programmable Peripheral Interface Figure 16. 6809/6502 Interface

____Pin Configurations (continued) ___________________Chip Topography

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.

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